

# Index

- active electronically scanned array (AESA), 211, 212, 243
- adhesion, 16, 27, 29, 30, 32, 44, 51, 52, 54, 55, 58, 59, 64, 66, 70, 75, 85
- advanced design system (ADS), *see* circuit modeling
- alignment sensitivity, 125
- alumina (ceramic), 9, 114, 196
- aluminum (Al), 56, 232, 235, 243
- aluminum nitride (AlN), 8, 9, 243
- American Society for Testing and Materials (ASTM), 36, 40, 243
- amplitude compensation, xiii, 193, 194, 195, 197, 198, 200, 201, 223
- amplitude imbalance, xiii, 171, 175, 194, 202, 216, 223
- analog-to-digital converter (ADC), 98, 142, 242
- angular frequency, 87, 135, 196
- anisotropy, 18, 41, 44, 45, 59, 74
- antenna, xiii, 142, 177, 193, 210, 211, 212, 214, 215, 216, 219, 221, 223, 224, 225
- antipodal tapered slot antenna, *see* antenna
- ash, 48, 74
- aspect ratio, 12, 50
- asymmetric beam, 216, 219
- asymmetric lines, 88, 122, 155, 186
- attenuation, 5, 20, 24, 111, 112, 113, 114, 154, 156, 157, 159, 194, 195
- back-to-back, 4, 13, 14, 100, 167, 169, 215
- ball grid array (BGA), 2, 243
- balun, xiii, 27, 160, 161, 162, 163, 164, 165, 166, 167, 168, 169, 170, 171, 172, 173, 174, 175, 176, 177, 190, 191, 202, 214
- bandpass, 97, 122, 154
- bandwidth, 122, 137, 138, 161, 171, 191, 207, 243
- bandwidth ratio (BWR), 162, 165, 166, 243
- beam angle, 212, 222
- beam forming, 177, 184, 215, 224
- beam squint, 213, 222, 223
- biaxial, 42, 70
- blind via hole (BVH), *see* via
- bond wire, 2, 11, 60, 97, 100, 102, 103, 104, 105, 106, 109, 110, 114, 115, 117, 119, 123, 124, 126, 132, 133, 134, 135, 136, 140, 144, 148, 153, 154, 155, 184, 236, 238
- boresight, 221, 222, 223
- broadband, xiii, 21, 122, 160, 177, 178, 180, 181, 185, 187, 190, 191, 193, 194, 202, 203, 210, 215, 223, 224
- broadside-coupled, 122, 123, 160, 161, 162, 165, 186, *see also* Coupling
- buried via, *see* via
- burn-in, 199
- bypass capacitor, 98, 143, 202, 227
- calibration, 13, 82, 91, 100, 114, 181, 200, 219, 223, 229, 245
- impedance standard substrate (ISS), 13, 91, 245
- load-reflect-match (LRM), 13, 82, 91, 200, 245
- short-open-load-through (SOLT), 13, 181, 247
- through-reflect-line (TRL), 13, 100, 229, 247
- cantilever beam, 73
- capacitor plates, 133, 135
- carbon dioxide (CO<sub>2</sub>), 48, 243
- casting, 42, 44
- cavity, xii, 6, 8, 10, 20, 21, 22, 23, 24, 34, 36, 37, 38, 42, 53, 56, 58, 60, 61, 62, 63, 64, 67, 68, 69, 72, 74, 75, 76, 77, 78, 84, 85, 97, 98, 102, 114, 119, 128, 154, 202, 223, 226, 227, 229, 233
- cavity resonator, *see* resonator
- characteristic impedance ( $Z_0$ ), 9, 21, 24, 78, 79, 83, 86, 87, 98, 100, 102, 103, 104, 105, 112, 120, 144, 145, 156, 157, 159, 162, 165, 173, 174
- Chebyshev system, 179, 214
- chemical bonding, 29, 51
- chemical properties, 16, 48, 226
- chip-scale package (CSP), xii, 72, 73, 243, 248
- chip-on-board (CoB), 10, 243
- chip-on-flex (CoF), xii, 10, 84, 85, 243
- chip-on-glass (CoG), 10, 243
- chirality, 18
- cholesteric, 18
- circuit element extractor, *see* three-dimensional electromagnetic (EM) software

- circuit modeling, 12, 80, 97, 116, 117, 118, 119, 134, 136, 154, 180, 196, 197, 242
- cleaning, 44, 46, 56
- coefficient of hydroscopic expansion (CHE), 16, 243
- coefficient of thermal expansion (CTE), 6, 10, 16, 18, 19, 45, 58, 202, 227, 230, 238, 243
- collected volatile condensable material (CVCN), 35, 36, 243
- color, 27, 47, 48, 69
- combiner, *see* Wilkinson power divider–splitter common mode, 5, 166
- computer-aided design (CAD), v, 10, 11, 191, 243
- conductive paste, 51, 98, 128, 129
- conductor loss, 47, 111, 112, 117, 157, 195
- coplanar waveguide (CPW), 91, 107, 108, 109, 112, 114, 117, 150, 159, 161, 190, 200, 243, 248
- copper (Cu), xii, 6, 8, 12, 27, 29, 30, 39, 41, 42, 43, 44, 45, 46, 47, 50, 51, 55, 56, 59, 60, 62, 70, 73, 74, 75, 78, 80, 85, 86, 98, 109, 110, 114, 135, 144, 199, 202, 227, 238, 243
- coupling, 1, 88, 119, 122, 123, 124, 126, 128, 129, 131, 136, 138, 139, 161, 170, 184, 185, 186, 187, 189, 190, 191, 192, 202, 223, *see also* hybrid coupler, edge-coupled, broadside-coupled
- covercoat, *see* coverlay
- coverlay, 47
- cross-talk, 119, 144, 146, 200, *see also* isolation
- cutoff frequency, 166, 244
- decoupling capacitor. *see* bypass capacitor
- de-embedding, 13, 80
- defected ground structure (DGS), 174, 243
- delay line, viii, xiii, 85, 86, 87, 89, 193, 194, 195, 196, 197, 200, 201, 202, 245
- detuning capacitance, 87
- developer, 47
- die attach, 10, 98, 202, 232, 243
- dielectric constant, 10, 16, 20, 21, 22, 23, 24, 25, 26, 39, 78, 87, 103, 105, 106, 112, 145, 159, 160, 162, 196, 214, 242
- dielectric loss, 3, 4, 10, 88, 111, 112, 113, 159, 195
- differential mode, 5, 160, 162, 166, 224
- dimensional stability, 16, 20, 27, 29
- direct chip attach (DCA). *see* Die Attach
- directivity, 184, 210
- discoloration, *see* color
- dissipation factor, *see* loss tangent
- divider, *see* Wilkinson power divider–splitter
- down-converter, 98, 142, 143, 147, 148, 149, 150, 151, 152, 153, 154
- driver amplifier, 142, 150
- dual in-line package (DIP), 2, 243
- e-beam, *see* electron beam physical vapor deposition
- edge-coupled, 122, 161, *see also* coupling
- electrical sensitivity, 109
- electroless nickel, immersion gold (ENIG), 55, 244
- electroless nickel, immersion palladium, immersion gold (ENIPIG), 55, 244
- electromagnetic (EM) software, 99, 100, 103
- electron beam physical vapor deposition (EBPVD), 44, 244
- electroplating, *see* plating
- embrittlement, 55, 56
- epoxy, 6, 19, 29, 67, 68, 70, 72, 84, 97, 226
- eutectic, 72, 150
- even-mode matching network (EMMN), viii, 167, 168, 169, 202, 203, 204, 208, 209, 210, 244
- feed-through, xii, 3, 13, 14, 72, 97, 98, 100, 101, 102, 105, 109, 110, 111, 112, 114, 115, 116, 117, 118, 119, 120, 121, 122, 132, 133, 134, 135, 138, 140, 141, 142, 144, 147, 148, 152, 153, 154, 157
- field programmable gate array (FPGA), 218, 219, 244
- filter, xii, xiii, 98, 133, 134, 135, 140, 141, 142, 154
- fine leak, *see* leak testing
- finite element method (FEM), 11, 12, 78, 102, 104, 108, 111, 119, 123, 133, 135, 136, 137, 145, 146, 154, 179, 181, 216, 244
- first-level interconnect, 73
- flatness (physical), *see* planarity
- flexibility, xi, 1, 19, 27, 32, 38, 224
- foil copper clad laminates (FCCL), 43, 44, 244
- FR-4, 26, 52, 244
- freeze expansion, 227, 233, 234, 235, 236, 238
- gain (electrical), 119, 121, 142, 150, 151, 152, 153, 154, 155, 194, 202, 205, 208, 210, 216, 217, 218, 219, 223, 229, 231, 232, 233, 234, 235, 236, 238, 239
- gallium arsenide (GaAs), 14, 30, 31, 32, 51, 60, 66, 67, 155, 178, 202, 218, 244
- generator, *see* signal generator (SG)
- gold (Au), 3, 44, 47, 51, 55, 56, 70, 72, 84, 144, 202, 227, 243, 244
- gross leak, *see* leak testing
- ground backed co-planar waveguide (CPWG), 100, 105, 106, 107, 108, 109, 112, 114, 123, 124, 128, 130, 243
- group delay, 93, 169, 171, 173, 197, 199, 201
- half-power beamwidth (HPBW), 216, 244
- handling techniques, xii, 1, 58, 59, 66, 70, 74, 85, 236

- harmonic distortion  
 second-order (HD2), 205, 206, 207, 210  
 third-order (HD3), 206, 207, 244  
 HBA, *see* p-hydroxybenzoic acid (HBA)  
 HD2, *see* second order harmonic distortion (HD2)  
 HDI, *see* high-density Interconnect (HDI)  
 heat distortion temperature (HDT), *see* melting temperature  
 hermetic requirement, xi, xii, xiii, 1, 2, 8, 9, 10, 16, 17, 19, 32, 34, 35, 36, 38, 39, 48, 69, 72, 73, 74, 85, 94, 97, 122, 226  
 high-density interconnect (HDI), 46, 95, 244  
 high-temperature storage (HTS), 231, 245  
 6-hydroxy-2-naphthoic acid (HNA), 18, 19, 20, 244  
 horn antenna, *see* antenna  
 humidity, xii, 7, 16, 24, 25, 26, 27, 34, 35, 227, 233, 234, 235  
 hybrid coupler, viii, xiii, 160, 174, 184, 185, 186, 187, 188, 189, 190, 191, 192  
 hybrid packaging, 8, 84, 85, 89, 93, 94, 96  
 IMD2, *see* intermodulation distortion, second-order  
 impedance standard substrate (ISS), *see* calibration  
 inductance compensation, 87, 102, 103, 104, 105, 106  
 inertness, xi, 34, 41, 43, 44, 48, 73, 226  
 injection molding, *see* molding  
 insertion loss, xiii, 4, 5, 14, 73, 79, 82, 83, 84, 88, 91, 92, 94, 97, 104, 106, 108, 115, 116, 117, 118, 119, 122, 123, 132, 137, 140, 141, 144, 154, 166, 175, 176, 177, 181, 194, 197, 200, 215, 218  
 integrated resistors, 177  
 interelement spacing (for phased-array antennas), 212  
 intermediate frequency (IF), 98, 142  
 intermetallic compound (IMC), 55, 56, 245  
 intermodular distortion  
 second-order (IMD2), 207, 208, 210, 223  
 third-order (IMD3), 208, 245  
 intersymbol interference (ISI), 212, 245  
 IPC, 32, 33, 40, 72, 245  
 isolation, 166, 181, 187, 188, 189, 200, *see also* cross-talk vii, 119  
 JEDEC, xiii, 71, 72, 245  
 known good-die-(KGD) Switches, 199, 200, 245  
 Ku-band, xiii, 146, 240  
 lamination, vi, vii, 17, 44, 50, 51, 52, 55, 70, 74, 162  
 land grid array (LGA), 2, 10, 245  
 laser processing, 48, 49, 61, 74  
 lead (Pb), 55, 56, 246  
 leak testing, xii, 5, 8, 34, 36, 37, 38, 39, 97, 154, 226  
 lid processing, vi, 60, 61, 67  
 line-and-space features, 47, 48, 85  
 lithography, 46, 47, 58  
 load-reflect-match calibration (LRM), *see* calibration  
 lobe (antenna), 214, 215, 216, 223  
 local oscillator (LO), 142, 144, 146, 147, 150, 225, 245  
 long time delay (LTD), *see* delay line  
 loss tangent (DF,  $\tan \delta$ ,  $\tan d$ ), 9, 20, 21, 23, 24, 25, 26, 39, 42, 78, 111, 112, 113, 159, 195, 243, 247  
 low-noise amplifier (LNA), xii, 5, 98, 119, 142, 144, 150, 151, 152, 153, 154, 217, 218, 219, 245  
 low-temperature co-fired ceramic (LTCC), 8, 155, 214, 245  
 LRM, *see* calibration  
 lumped-element circuit, vii, 117, 132, 136, 141, 156  
 lyotropic, 17  
 main-chain liquid crystals, 17, 18  
 material analyzer, 24  
 meander, 133, 186, 190  
 mechanical drilling, 48, 60, 61, 98  
 mechanical locking, 29, 51  
 mechanical shock, 227, 236, 237, 239  
 melting temperature, 19, 20, 28, 29, 43, 50, 52, 54, 55, 62, 64, 65, 66, 74, 114, 162, 199, 227, 244  
 mesogens, 17  
 mesophase, 17  
 metal-insulator-metal (MIM) capacitor, 132, 133, 135, 137, 246  
 metal thickness, 6, 47, 109, 135  
 metallization, xii, 43, 44, 77, 128, 132  
 method of moments (MoM), 11, 80, 89, 167, 168, 169, 170, 171, 187, 196, 215, 246  
 microelectromechanical system (MEMS), vi, viii, xii, xiii, 8, 34, 35, 36, 39, 40, 71, 72, 73, 74, 75, 76, 77, 78, 83, 84, 85, 86, 88, 89, 90, 93, 94, 95, 96, 193, 196, 197, 199, 200, 224, 240, 245  
 microstrip, 13, 23, 24, 27, 28, 29, 78, 79, 89, 100, 102, 103, 104, 105, 106, 109, 111, 112, 114, 117, 123, 128, 130, 135, 144, 145, 146, 153, 154, 155, 157, 159, 160, 161, 162, 163, 165, 166, 170, 174, 184, 186, 191, 194, 195, 200, 248  
 microvia, 80, *see* via  
 military standard (Mil-Std), xii, xiii, 14, 36, 227, 229, 231, 234, 237, 239, 240, 241, 245  
 milling process, 48, 61, 70, 202

- mismatch, 1, 2, 3, 4, 6, 14, 102, 115, 117, 166, 179, 194, 200, 205, 223
- mixer, 98, 142, 143, 144, 146, 150, 153, 154
- module, vii, xii, xiii, 9, 11, 16, 43, 72, 73, 84, 85, 86, 94, 95, 97, 98, 132, 142, 143, 144, 147, 148, 149, 150, 151, 152, 153, 154, 193, 194, 195, 197, 199, 200, 202, 203, 204, 206, 209, 210, 211, 217, 218, 219, 223, 224, 227, 229, 232, 245
- moisture, xiii, 1, 6, 7, 8, 9, 10, 16, 19, 20, 24, 29, 34, 35, 39, 69, 72, 73, 84, 97, 154, 226, 227, 233, 234, 235
- molding, xii, 2, 9, 10, 16, 41, 42, 54, 58, 60, 67, 68, 69, 70, 71, 226
- monolithic microwave integrated circuit (MMIC), 7, 70, 94, 95, 97, 98, 102, 103, 114, 119, 123, 129, 144, 147, 191, 202, 205, 217, 218, 226, 238, 240, 246
- Monte-Carlo method, 99
- mounting techniques, 59, 85, 97, 114, 128, 148, *see also* Surface Mount (SMT) 55, 56, 59
- multi-chip module (MCM), *see* module
- multilayer, xii, xiii, 1, 6, 7, 8, 39, 41, 42, 43, 46, 48, 50, 51, 55, 57, 58, 63, 70, 72, 73, 94, 97, 98, 99, 100, 114, 122, 127, 143, 160, 163, 165, 167, 170, 171, 172, 173, 174, 177, 178, 182, 184, 185, 186, 187, 189, 190, 193, 194, 199, 200, 216, 217, 223, 227
- nematic liquid crystal arrangement, 18
- neper (Np), 87, 194, 195, 242, 246
- network analyzer (NA), 13, 21, 91, 114, 175, 181, 187, 200, 229, 246
- nickel (Ni), 55, 70, 244, 246
- on-wafer measurement, 13, 82, 91, 93, 97, 100, 107, 108, 114, 120, 128, 148, 153, 154, 164, 165, 175, 181, 187, 200, 215
- optical comparator, 50, 51
- outgassing, vi, 17, 34, 35, 36, 39, 40, 72
- overmold, *see* molding
- oxidation, 55, 144
- $P_{1dB}$ , 1 dB compression point, 5, 153, 202, 204, 205, 206, 207, 210, 223
- palladium (Pd), 55, 246
- peel strength, 29, 30, 32, *see also* adhesion
- pellet, 16, 41, 42, 69
- permeability/permeation, 8, 10, 16, 19, 34, 40, 84, 135, 226, 242
- phase imbalance, xiii, 169, 171, 175
- phase shifter, xii, 73, 84, 85, 86, 88, 89, 90, 91, 92, 93, 94, 95, 96, 193, 212, 217, 218, 223
- phase variation, 84
- phased-array antenna, xiii, 177, 193, 210, 211, 212, 213, 214, 216, 217, 218, 219, 223, 224
- photolithography, *see* lithography
- photoresist, *see* lithography
- p-hydroxybenzoic acid (HBA), 18, 19, 20, 244
- physical vapor deposition (PVD), 44
- pitch, 9, 47, 82, 91, 107, 114
- planarity, 27, 56, 67
- plated through hole (PTH), *see* via
- plating, vi, 13, 43, 44, 45, 46, 47, 48, 50, 51, 55, 56, 85, 162, 171, 199
- polyimide, 25, 33, 54
- polystyrene, 181
- power added efficiency (PAE), 202
- power amplifier (PA), viii, xiii, 5, 96, 202, 203, 204, 205, 206, 207, 208, 209, 210, 223, 246
- printed circuit board (PCB), vi, xii, 3, 6, 10, 17, 18, 41, 46, 47, 50, 51, 55, 58, 70, 97, 100, 108, 114, 115, 117, 121, 127, 128, 129, 130, 146, 148, 150, 151, 162, 163, 184, 190, 200, 214, 246
- probe measurement, *see* on-wafer measurement
- profilometer, *see* planarity
- propagation velocity, 87
- pull test, *see* adhesion
- punching, *see* stamping
- push-pull amplifier, xiii, 193
- quad flat no-lead (QFN), 2, 10, 56, 57, 60, 67, 227, 240, 246
- quarter-wavelength, 12, 132, 179, 184
- radiation, 4, 23, 36, 83, 111, 214, 215, 216, 217, 219, 222
- rapid thermal transition, viii, 227, 230, 239
- reactive ion etching (RIE), 27, 28, 59, 247
- receiver, xii, xiii, 5, 98, 142, 147, 150, 151, 154, 193, 207, 211, 215, 217, 219, 224, 225
- reflection, *see* mismatch
- reflow, 27, 28, 54, 75, 76
- relative dielectric constant, *see* dielectric constant
- relative humidity conditioning 85 °C /85%, ix, 227, 233, 239
- relay, *see* switch
- resin, 41, 196
- resonance, 1, 10, 11, 12, 19, 20, 21, 93
- resonator, 20, 21, 22, 23, 24, 42
- return loss, xii, 4, 27, 73, 79, 82, 83, 88, 89, 91, 92, 94, 97, 98, 101, 104, 106, 108, 115, 116, 119, 121, 124, 130, 131, 144, 151, 154, 165, 166, 171, 172, 175, 176, 177, 178, 179, 180, 181, 187, 190, 197, 198, 200, 205, 209, 216, 248
- ring resonator, *see* resonator
- roll-to-roll processing, 57
- roughness, 29, 43, 44, 46, 111
- satellite communications (SATCOM), 210, 247
- scanning electron microscope (SEM), 13, 27, 28, 129, 131, 138, 247

- scattering parameters (S-parameters), 3, 5,  
 13, 14, 82, 88, 91, 127, 167, 169, 203,  
*see also* insertion loss, return loss, isolation,  
 cross-talk
- seed layer, *see* adhesion
- selective sealing, xii, 64, 70
- short-open-load-through calibration (SOLT),  
*see* calibration
- side-chain, 17
- signal generator (SG), 206, 247
- silicon (Si), xii, 29, 30, 31, 32, 51, 74, 75, 77, 78,  
 85, 225, 247
- single in-line package (SIP), 2
- single-pole 4-throw, *see* switch
- single-pole single-throw, *see* switch
- skin depth ( $\delta$ ), 22, 46, 47, 135
- small-outline integrated circuit (SOIC), 2, 247
- smectic liquid crystal arrangement, 18
- solder, 2, 3, 6, 13, 47, 51, 55, 57, 67, 72, 94, 97,  
 98, 109, 110, 114, 115, 128, 129, 148, 150,  
 215
- solder mask, 47
- spectrum analyzer (SA), 150, 154, 247
- spurious free dynamic range (SFDR), 206, 247
- sputter-plating, *see* plating
- stamping, 36, 59, 64, 70, 114, 128
- stripline, 79, 144, 145, 146, 153, 154, 156
- submount, 97
- surface mount (SMT), vii, xi, xii, xiii, 2, 3, 10, 64,  
 65, 67, 69, 97, 98, 99, 105, 114, 115, 116, 119,  
 122, 123, 142, 154, 156, 167, 193, 227, 229,  
 241, 247
- surface roughness, *see* roughness
- switch, xii, xiii, 35, 36, 71, 72, 73, 74, 76,  
 78, 79, 80, 81, 82, 83, 84, 85, 86, 87, 88, 89,  
 91, 93, 94, 95, 96, 193, 194, 196, 197, 199,  
 200, 247
- switched circuit, 86, 91, 94, 96
- system-in-package (SiP), 10, 16, 247
- tan  $\delta$ , *see* loss tangent
- T-junction, 88
- temperature step stressing, *see* thermal cycling
- thermal cycling, 8, 227, 229, 239
- thermal dissipation, 7
- thermal profile, 54
- thermal shock, viii, 51, 227, 229, 232, 233, 239
- thermal simulation, 12, 66, 70
- thermoccompression, *see* lamination
- thermoplastic, 9, 16, 18, 19, 36, 50
- thermoset, 50
- three-dimensional electromagnetic (EM)  
 software, 101, 104, 244, *see also* finite  
 element method (FEM), method of  
 moments (MoM)
- through-reflect-line (TRL), *see* calibration
- time-domain reflectometry (TDR), 14, 247
- tin (Sn), 55, 94, 247
- titanium (Ti), 44, 247
- transmission line (TL), *see* microstrip, stripline,  
 coplanar waveguide (CPW), ground backed  
 co-planar waveguide (CPWG)
- transmit and receive (T/R), 210, 211, 247
- true-time delay (TTD), xiii, 84, 86, 96, 194,  
 212, 247
- ultra-wideband (UWB), 177, 248,  
*see also* broadband
- Van der Waals forces, *see* adhesion
- V-band, 177
- very large scale integration (VLSI), 211, 248
- via, xii, 2, 9, 13, 29, 45, 46, 47, 48, 49, 50, 51,  
 55, 70, 73, 74, 77, 78, 80, 83, 85, 89, 94,  
 97, 98, 100, 101, 102, 105, 109, 114, 117,  
 118, 119, 122, 123, 124, 126, 128, 129,  
 131, 132, 134, 135, 136, 141, 144, 154,  
 162, 170, 171, 179, 186, 199, 200, 227,  
 230, 238, 240
- vibration testing, 227, 236, 237, 238
- voltage standing wave ratio (VSWR), *see* return  
 loss
- wafer-scale packaging, 30, 72, *see also* chip-scale  
 package 2, 3
- water (H<sub>2</sub>O), 19, 226, 235, 240
- W-band, 177
- wet chemistry, 48
- Wilkinson power divider-splitter, viii, xiii, 160,  
 166, 177, 178, 179, 180, 181, 182, 184, 191,  
 206, 215, 224
- wire bond, *see* bond wire
- X-band, 73, 82, 86, 94, 96
- yttrium aluminum garnet (YAG), 48, 248